

## SN74AHC08Q-Q1 Automotive Quadruple 2-Input Positive-and Gate

### 1 Features

- Qualified for Automotive Applications
- Operating Range 2-V to 5.5-V  $V_{CC}$
- EPIC™ (Enhanced-Performance Implanted CMOS) Process
- Latch-Up Performance Exceeds 250 mA Per JESD 17

### 2 Description

This device is a quadruple 2-input positive-AND gate that performs the Boolean function  $Y = A \cdot B$  or  $Y = \overline{A} + \overline{B}$  in positive logic.

#### Package Information

PART NUMBER	PACKAGE <sup>1</sup>	PACKAGE SIZE <sup>2</sup>
SN74AHC08Q-Q1	D (SOIC, 14)	8.65 mm × 6 mm
	PW (TSSOP, 14)	5.00 mm × 6.4 mm
	BQA (WQFN, 14)	3 mm × 2.5 mm

1. For all available packages, see the orderable addendum at the end of the data sheet.
2. The package size (length × width) is a nominal value and includes pins, where applicable.



Figure 2-1. Logic Diagram (Positive Logic)



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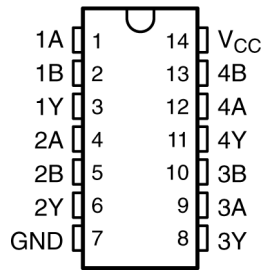
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## 3 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from Revision C (April 2008) to Revision D (June 2023)</b>	<b>Page</b>
• Added <i>Package Information</i> table, <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Device Functional Modes</i> , <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section .....	1
• Added BQA package to <i>Package Information</i> table.....	1
• Updated thermal values for PW package from $R\theta_{JA} = 113$ to $147.7$ , all values in $^{\circ}\text{C}/\text{W}$ .....	5
• Added thermal value for $R\theta_{JA}$ : BQA = $88.3$ , all values in $^{\circ}\text{C}/\text{W}$ .....	5

## 4 Pin Configuration and Functions



**Figure 4-1. D or PW Package (Top View)**

**Table 4-1. Pin Functions**

PIN		TYPE	DESCRIPTION
NAME	NO.		
1A	1	Input	Channel 1, Input A
1B	2	Input	Channel 1, Input B
1Y	3	Output	Channel 1, Output Y
2A	4	Input	Channel 2, Input A
2B	5	Input	Channel 2, Input B
2Y	6	Output	Channel 2, Output Y
GND	7	—	Ground
3Y	8	Output	Channel 3, Output Y
3A	9	Input	Channel 3, Input A
3B	10	Input	Channel 3, Input B
4Y	11	Output	Channel 4, Output Y
4A	12	Input	Channel 4, Input A
4B	13	Input	Channel 4, Input B
V <sub>CC</sub>	14	—	Positive Supply

## 5 Specifications

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	-0.5	7	V
V <sub>I</sub> <sup>1</sup>	Input voltage range	-0.5	7	V
V <sub>O</sub> <sup>1</sup>	Output voltage range	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	(V <sub>I</sub> < 0)	-20	mA
I <sub>OK</sub>	Output clamp current	(V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±20	mA
I <sub>O</sub>	Continuous output current	(V <sub>O</sub> = 0 to V <sub>CC</sub> )	±25	mA
	Continuous current through V <sub>CC</sub> or GND		±50	mA
T <sub>stg</sub>	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 5.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per AEC Q100-002 <sup>1</sup>	±2000	V

- (1) AEC Q100-002 indicates that HBM stressing must be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

### 5.3 Recommended Operating Conditions

over recommended operating free-air temperature range (unless otherwise noted)<sup>1</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	2	5.5	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V	1.5	V
		V <sub>CC</sub> = 3 V	2.1	
		V <sub>CC</sub> = 5.5 V	3.85	
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V	0.5	V
		V <sub>CC</sub> = 3 V	0.9	
		V <sub>CC</sub> = 5.5 V	1.65	
V <sub>I</sub>	Input voltage	0	5.5	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2 V	-50	mA
		V <sub>CC</sub> = 3.3 V ± 0.3 V	-4	
		V <sub>CC</sub> = 5 V ± 0.5 V	-8	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2 V	50	mA
		V <sub>CC</sub> = 3.3 V ± 0.3 V	4	
		V <sub>CC</sub> = 5 V ± 0.5 V	8	
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 3.3 V ± 0.3 V	100	ns/V
		V <sub>CC</sub> = 5 V ± 0.5 V	20	
T <sub>A</sub>	Operating free-air temperature	-40	125	°C

- (1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## 5.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>	SN74AHC08Q-Q1			UNIT
	D (SOIC)	PW (TSSOP)	BQA (WQFN)	
	14 PINS	14 PINS	14 PINS	
R <sub>θJA</sub> Junction-to-ambient thermal resistance	86	147.7	88.3	°C/W

(1) For more information about traditional and new thermal metrics, see the [IC Package Thermal Metrics](#)

## 5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C TO 125°C		T <sub>A</sub> = -40°C TO 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	2 V	1.9	2		1.9		1.9	V	
		3 V	2.9	3		2.9		2.9		
		4.5 V	4.4	4.5		4.4		4.4		
	I <sub>OH</sub> = -4 mA	3 V	2.58		2.48		2.48			
	I <sub>OH</sub> = -8 mA	4.5 V	3.94		3.8		3.8			
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	2 V			0.1		0.1	0.1	V	
		3 V			0.1		0.1	0.1		
		4.5 V			0.1		0.1	0.1		
	I <sub>OL</sub> = 4 mA	3 V		0.36		0.5	0.44			
	I <sub>OL</sub> = 8 mA	4.5 V		0.36		0.5	0.44			
I <sub>I</sub>	A or B inputs	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V		±0.1		±1	±1	μA	
I <sub>CC</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V		2		20	20	μA	
C <sub>i</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		4 10				pF	

## 5.6 Switching Characteristics, V<sub>CC</sub> = 3.3 V ± 0.3 V

over recommended operating free-air temperature range, V<sub>CC</sub> = 3.3 V ± 0.3 V (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C TO 125°C		T <sub>A</sub> = -40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	Y	C <sub>L</sub> = 15 pF	6.2	8.8		1	10.5	1	10.5	ns
t <sub>PHL</sub>				6.2	8.8		1	10.5	1	10.5	
t <sub>PLH</sub>	A or B	Y	C <sub>L</sub> = 50 pF	8.7	12.3		1	14	1	14	ns
t <sub>PHL</sub>				8.7	12.3		1	14	1	14	

## 5.7 Switching Characteristics, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$

over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C TO } 125^\circ\text{C}$		$T_A = -40^\circ\text{C TO } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A or B	Y	$C_L = 15\text{ pF}$		4.3	5.9	1	7	1	7	ns
$t_{PHL}$					4.3	5.9	1	7	1	7	
$t_{PLH}$	A or B	Y	$C_L = 50\text{ pF}$		5.8	7.9	1	9	1	9	ns
$t_{PHL}$					5.8	7.9	1	9	1	9	

## 5.8 Noise Characteristics

$V_{CC} = 5\text{ V}$ ,  $C_L = 50\text{ pF}$ ,  $T_A = 25^\circ\text{C}$ <sup>1</sup>

PARAMETER		MIN	MAX	UNIT
$V_{OL(P)}$	Quiet output, maximum dynamic $V_{OL}$		0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic $V_{OL}$		-0.8	V
$V_{IH(D)}$	High-level dynamic input voltage	3.5		V
$V_{IL(D)}$	Low-level dynamic input voltage		1.5	V

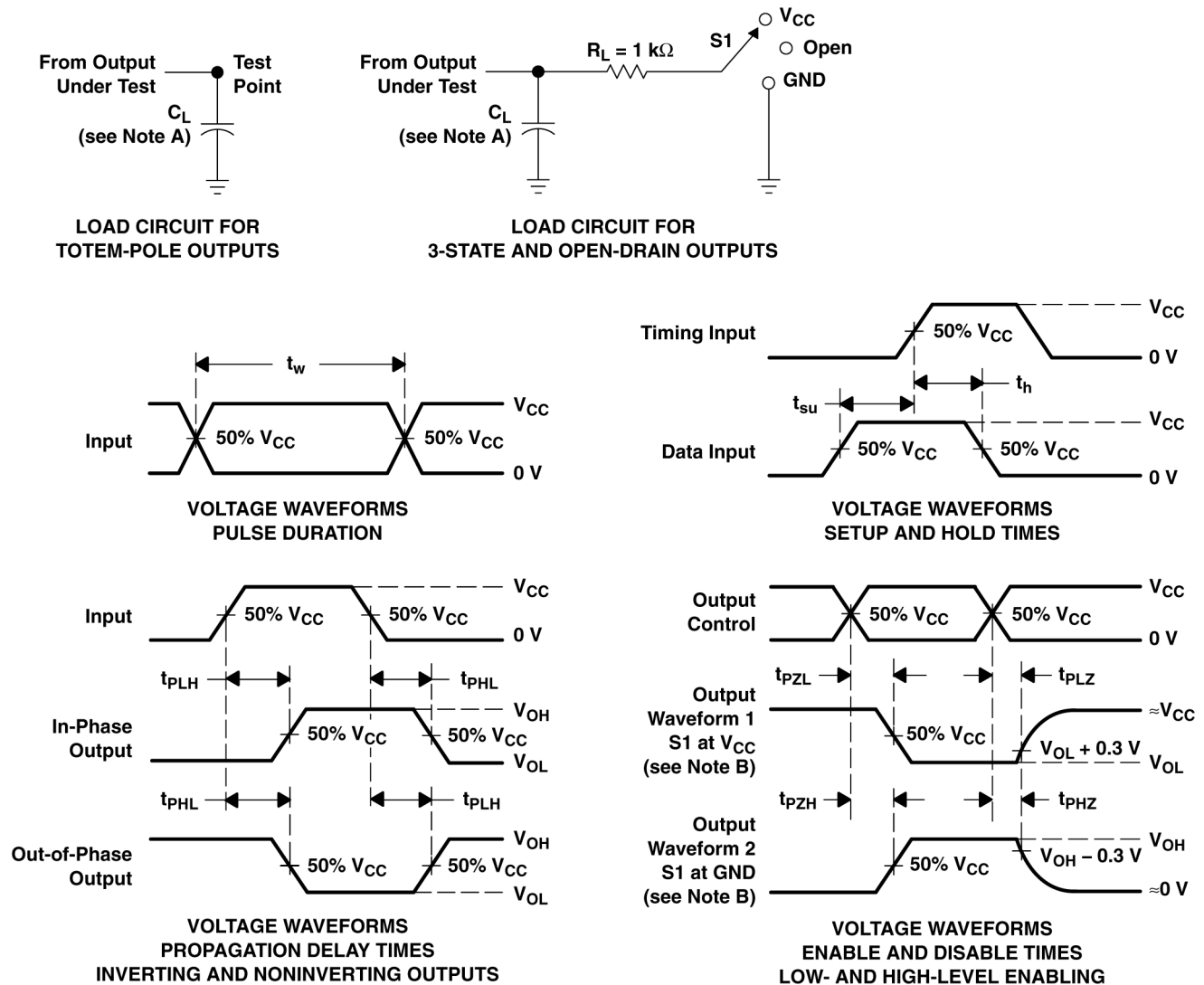
(1) Characteristics are for surface-mount packages only.

## 5.9 Operating Characteristics

$V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
$C_{pd}$	Power dissipation capacitance	No load, $f = 1\text{ MHz}$	18	pF

## 6 Parameter Measurement Information



- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 3$  ns,  $t_f \leq 3$  ns.
- D. The outputs are measured one at a time, with one input transition per measurement.

**Figure 6-1. Load Circuit and Voltage Waveforms**

TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{CC}$
$t_{PHZ}/t_{PZH}$	GND
Open Drain	$V_{CC}$

## 7 Detailed Description

### 7.1 Functional Block Diagram

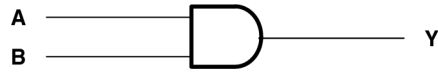


Figure 7-1. Logic Diagram (Positive Logic)

### 7.2 Device Functional Modes

Table 7-1. Function Table (Each Gate)

INPUTS		OUTPUT Y
A	B	
H	H	H
L	X	L
X	L	L



## 8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 8.1 Documentation Support

#### 8.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

**Table 8-1. Related Links**

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN74AHC08Q-Q1	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>

### 8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 8.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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### 8.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.  
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### 8.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 8.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 9 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AHC08QDRG4Q1	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM		AHC08Q	<a href="#">Samples</a>
SN74AHC08QDRQ1	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC08Q	<a href="#">Samples</a>
SN74AHC08QPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HA08Q	<a href="#">Samples</a>
SN74AHC08QPWRQ1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HA08Q	<a href="#">Samples</a>
SN74AHC08QWBQARQ1	ACTIVE	WQFN	BQA	14	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC08Q	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC08QPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHC08QPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHC08QWBQARQ1	WQFN	BQA	14	3000	180.0	12.4	2.8	3.3	1.1	4.0	12.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC08QPWRG4Q1	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74AHC08QPWRQ1	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74AHC08QWBQARQ1	WQFN	BQA	14	3000	210.0	185.0	35.0

## GENERIC PACKAGE VIEW

**BQA 14**

**WQFN - 0.8 mm max height**

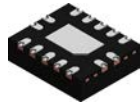
2.5 x 3, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



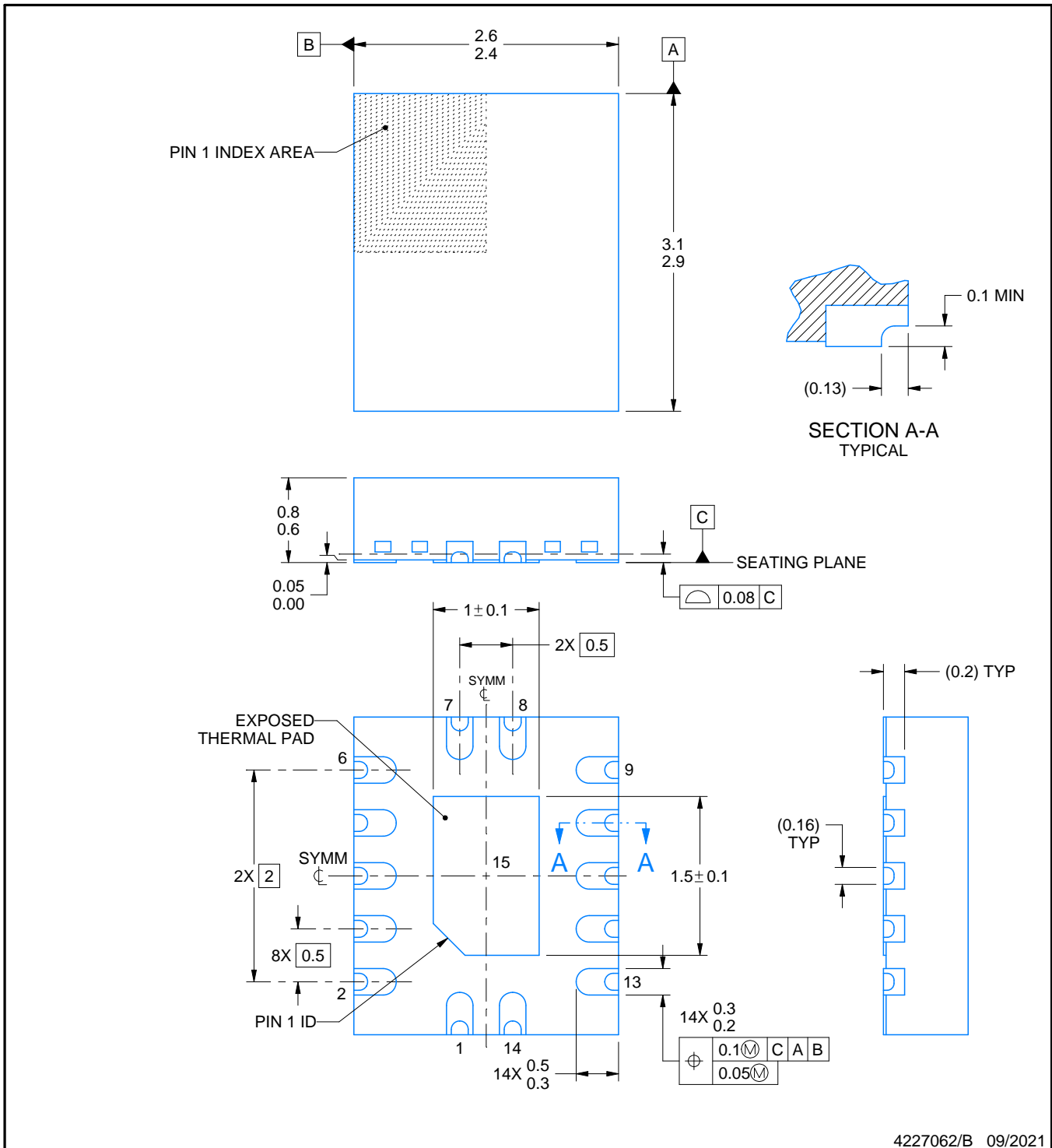
# BQA0014B



## PACKAGE OUTLINE

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



4227062/B 09/2021

### NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



# EXAMPLE BOARD LAYOUT

**BQA0014B**

**WQFN - 0.8 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



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NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

BQA0014B

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125 MM THICK STENCIL  
SCALE: 20X

EXPOSED PAD 15  
87% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

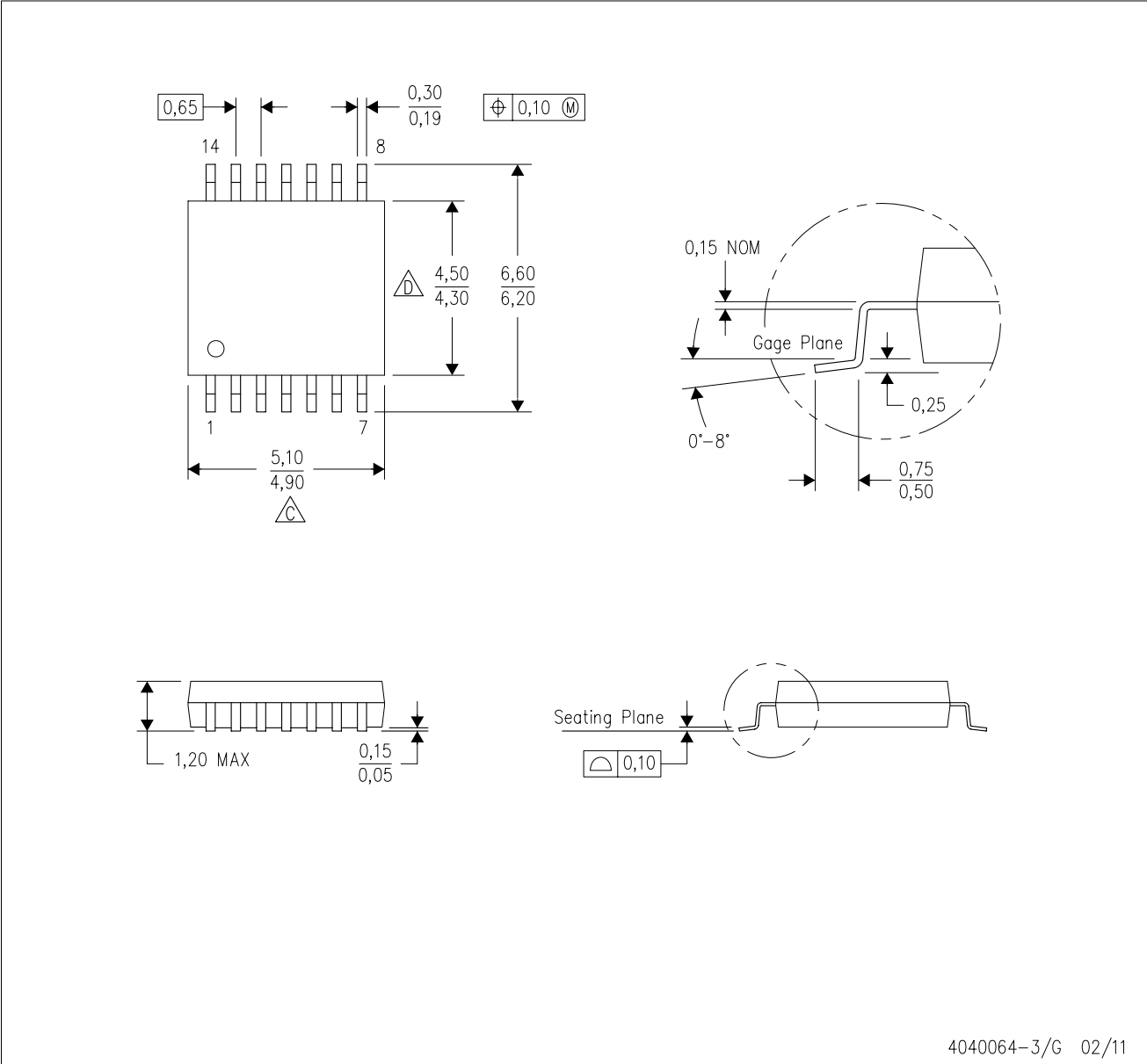


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AB.

**MECHANICAL DATA**

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040064-3/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

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